

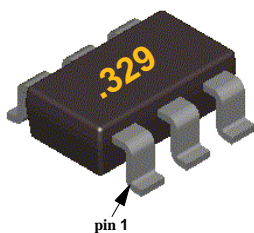
## FDC6329L Integrated Load Switch

### General Description

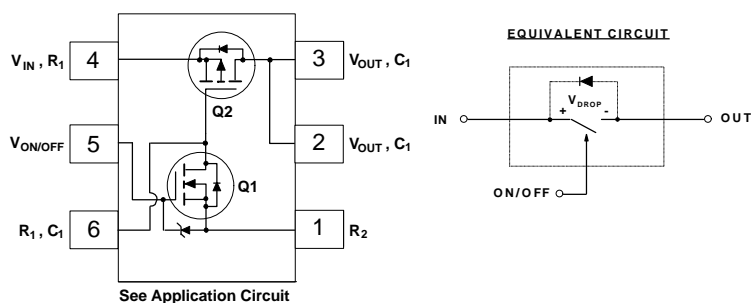
This device is particularly suited for compact power management in portable electronic equipment where 2.5V to 8V input and 2.5A output current capability are needed. This load switch integrates a small N-Channel power MOSFET (Q1) which drives a large P-Channel power MOSFET (Q2) in one tiny SuperSOT™-6 package.

### Features

- $V_{\text{DROP}}=0.2\text{V}$  @  $V_{\text{IN}}=5\text{V}$ ,  $I_{\text{L}}=2.8\text{A}$ .  $R_{\text{(ON)}} = 0.07\Omega$   $V_{\text{DROP}}=0.2\text{V}$  @  $V_{\text{IN}}=2.5\text{V}$ ,  $I_{\text{L}}=1.9\text{A}$ .  $R_{\text{(ON)}} = 0.105\Omega$ .
- Control MOSFET (Q1) includes Zener protection for ESD ruggedness (>6KV Human Body Model).
- High performance trench technology for extremely low on-resistance.
- SuperSOT™-6 package design using copper lead frame for superior thermal and electrical capabilities.



SuperSOT™-6



### Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FDC6329L	Units
$V_{\text{IN}}$	Input Voltage Range (Note 1)	2.5 - 8	V
$V_{\text{ON/OFF}}$	On/Off Voltage Range	1.5 - 8	V
$I_{\text{L}}$	Load Current - Continuous (Note 2)	2.5	A
	- Pulsed	10	
$P_{\text{D}}$	Maximum Power Dissipation (Note 2)	0.7	W
$T_{\text{J}}, T_{\text{STG}}$	Operating and Storage Temperature Range	-55 to 150	$^\circ\text{C}$
ESD	Electrostatic Discharge Rating MIL-STD-883D Human Body Model (100pf/1500Ohm)	6	kV

### THERMAL CHARACTERISTICS

$R_{\theta\text{JA}}$	Thermal Resistance, Junction-to-Ambient (Note 2)	180	$^\circ\text{C/W}$
$R_{\theta\text{JC}}$	Thermal Resistance, Junction-to-Case (Note 2)	60	$^\circ\text{C/W}$

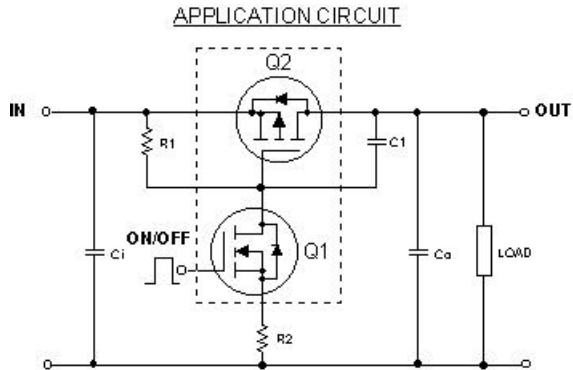
## Electrical Characteristics ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>OFF CHARACTERISTICS</b>						
$I_{FL}$	Forward Leakage Current	$V_{IN} = 8\text{ V}, V_{ON/OFF} = 0\text{ V}$			1	$\mu\text{A}$
<b>ON CHARACTERISTICS (Note 3)</b>						
$V_{DROP}$	Conduction Voltage	$V_{IN} = 5\text{ V}, V_{ON/OFF} = 3.3\text{ V}, I_L = 2.8\text{ A}$		0.12	0.2	V
		$V_{IN} = 2.5\text{ V}, V_{ON/OFF} = 3.3\text{ V}, I_L = 1.9\text{ A}$		0.14	0.2	
$R_{(ON)}$	$Q_2$ - Static On-Resistance	$V_{GS} = -5\text{ V}, I_D = -2.5\text{ A}$		0.047	0.07	$\Omega$
		$V_{GS} = -2.5\text{ V}, I_D = -2.0\text{ A}$		0.073	0.105	
$I_L$	Load Current	$V_{DROP} = 0.2\text{ V}, V_{IN} = 5\text{ V}, V_{ON/OFF} = 3.3\text{ V}$	2.8			A
		$V_{DROP} = 0.2\text{ V}, V_{IN} = 2.5\text{ V}, V_{ON/OFF} = 3.3\text{ V}$	1.9			

### Notes:

- Range of  $V_{in}$  can be up to 8V, but  $R_1$  and  $R_2$  must be scaled such that  $V_{GS}$  of  $Q_2$  does not exceed -8V.
- $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.
- Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

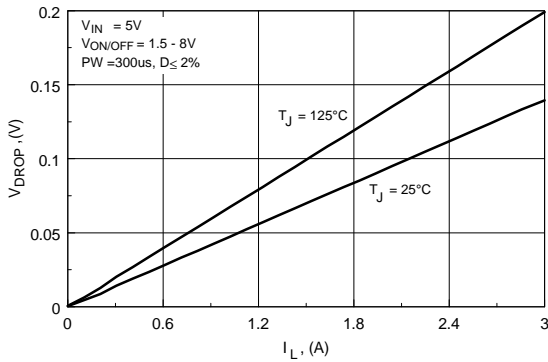
## FDC6329L Load Switch Application



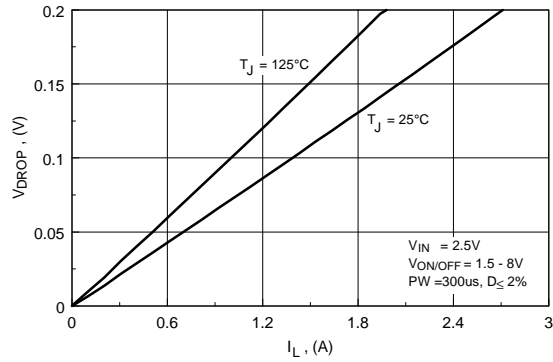
### External Component Recommendation:

- For applications where  $C_0 \leq 1\mu\text{F}$ .
- For slew rate control, select  $R_2$  in the range of  $1\text{ k} - 4.7\text{ k}\Omega$ .
- For additional in-rush current control,  $C_1 \leq 1000\text{ pF}$  can be added.
- Select  $R_1$  so that the  $R_1/R_2$  ratio ranges from 10 - 100.  $R_1$  is required to turn  $Q_2$  off.

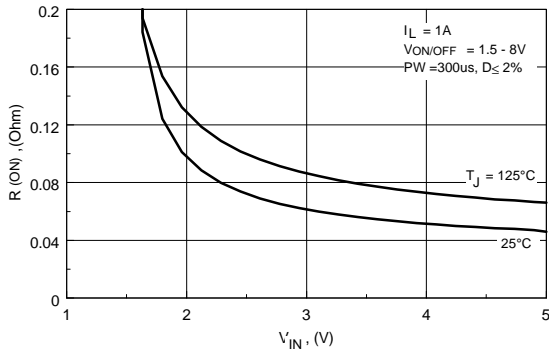
**Typical Electrical Characteristics** ( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise noted )



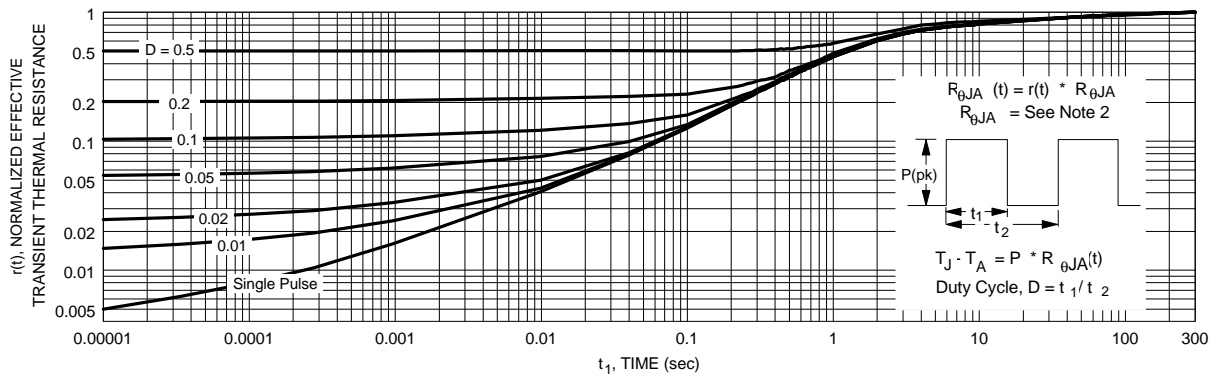
**Figure 1. Conduction Voltage Drop Variation with Load Current.**



**Figure 2. Conduction Voltage Drop Variation with Load Current.**



**Figure 3. On-Resistance Variation with Input Voltage.**

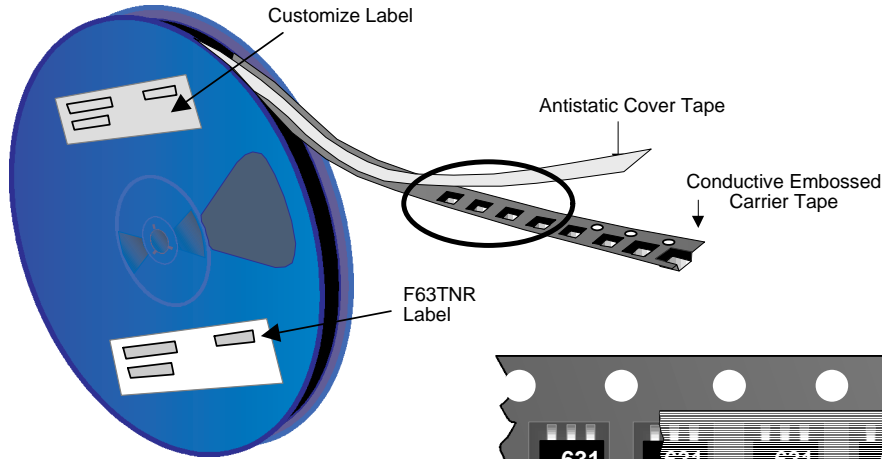


**Figure 4. Transient Thermal Response Curve.**

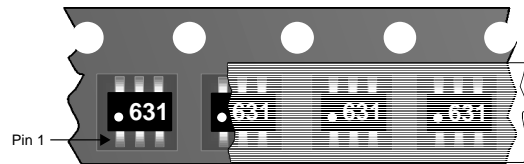
Thermal characterization performed using the conditions described in Note 2.  
Transient thermal response will change depending on the circuit board design.

# SuperSOT™-6 Tape and Reel Data and Package Dimensions

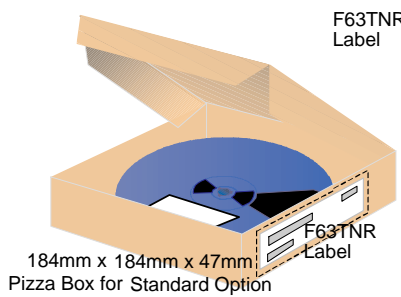
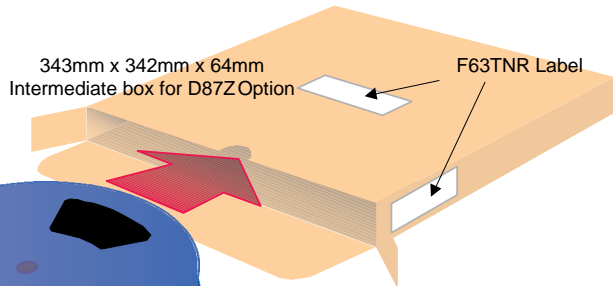
**SSOT-6 Packaging**  
Configuration: Figure 1.0



SSOT-6 Packaging Information		
Packaging Option	Standard (no flow code)	D87Z
Packaging type	TNR	TNR
Qty per Reel/Tube/Bag	3,000	10,000
Reel Size	7" Dia	13"
Box Dimension (mm)	184x187x47	343x343x64
Max qty per Box	9,000	20,000
Weight per unit (gm)	0.0158	0.0158
Weight per Reel (kg)	0.1440	0.4700
Note/Comments		



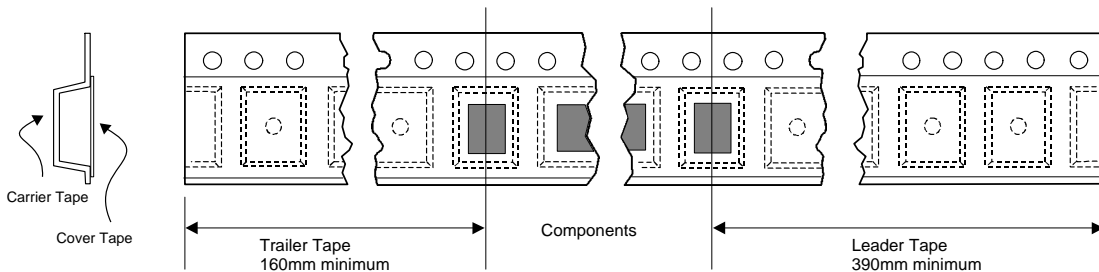
**SSOT-6 Unit Orientation**



**F63TNR Label sample**

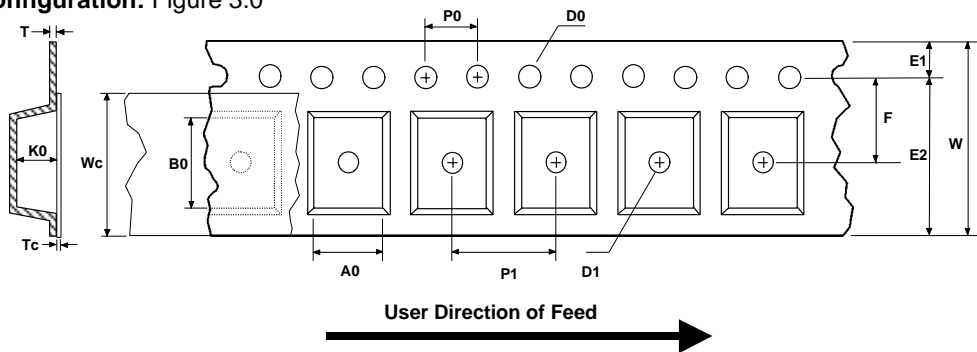


**SSOT-6 Tape Leader Trailer Configuration: Figure 2.0**



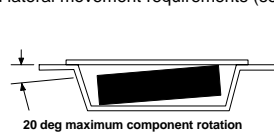
# SuperSOT™-6 Tape and Reel Data and Package Dimensions, continued

## SSOT-6 Embossed Carrier Tape Configuration: Figure 3.0

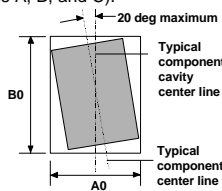


Dimensions are in millimeter														
Pkg type	A0	B0	W	D0	D1	E1	E2	F	P1	P0	K0	T	Wc	Tc
SSOT-6 (8mm)	3.23 +/-0.10	3.18 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.00 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.37 +/-0.10	0.255 +/-0.150	5.2 +/-0.3	0.06 +/-0.02

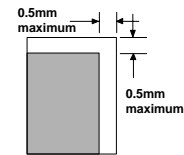
Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)  
Component Rotation

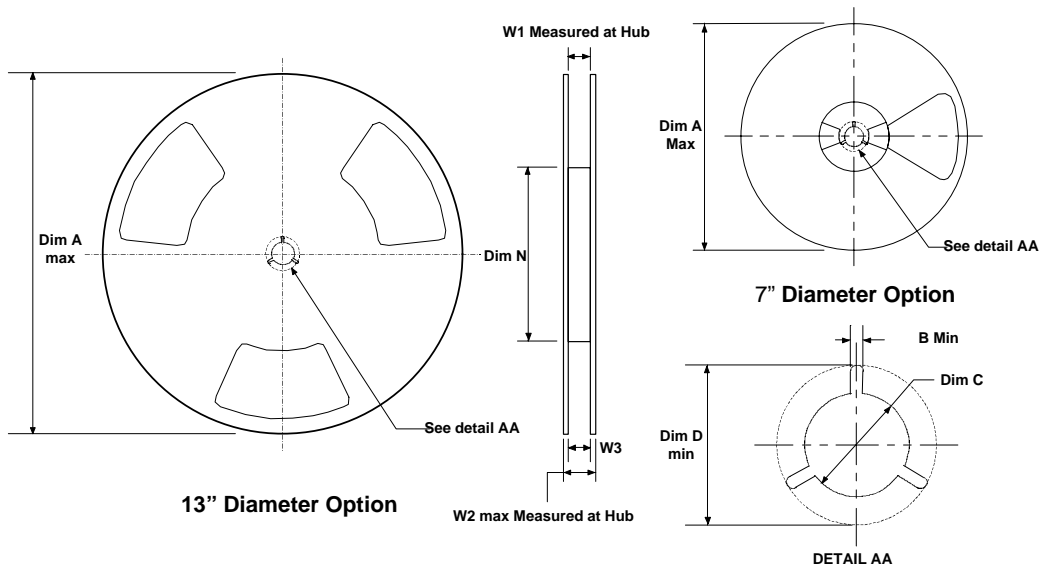


Sketch B (Top View)  
Component Rotation



Sketch C (Top View)  
Component lateral movement

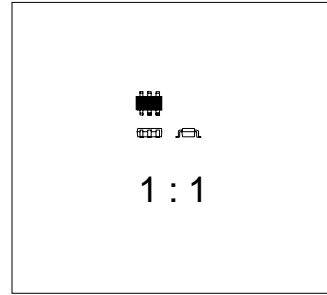
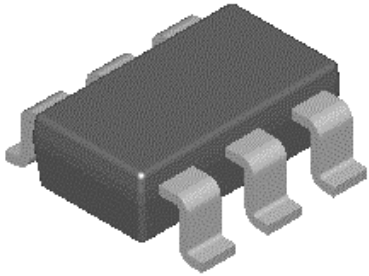
## SSOT-6 Reel Configuration: Figure 4.0



Dimensions are in inches and millimeters									
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9

**SuperSOT™-6 Tape and Reel Data and Package Dimensions, continued**

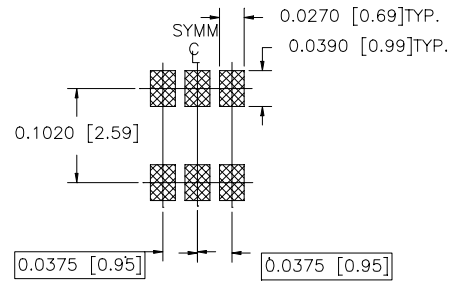
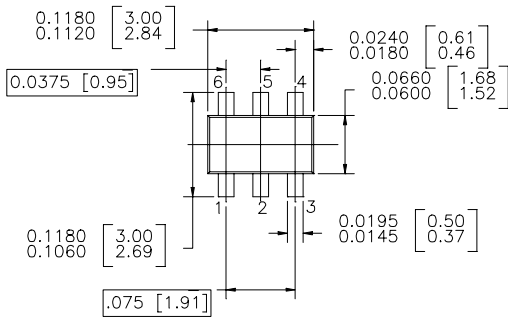
**SuperSOT™-6 (FS PKG Code 31, 33)**



Scale 1:1 on letter size paper

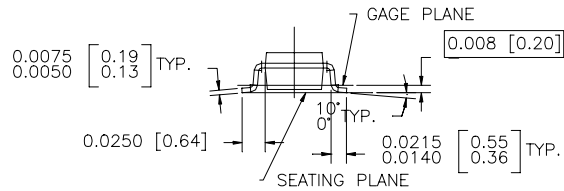
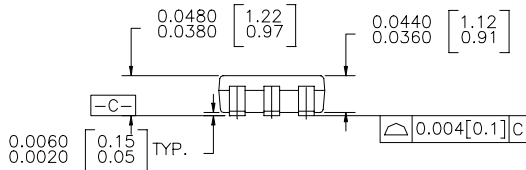
Dimensions shown below are in:  
inches [millimeters]

Part Weight per unit (gram): 0.0158



LAND PATTERN RECOMMENDATION

CONTROLLING DIMENSION IS INCH  
VALUES IN [ ] ARE MILLIMETERS



SUPER SOT 6 LEADS

NOTES : UNLESS OTHERWISE SPECIFIED

1.0 STANDARD LEAD FINISH : 150 MICRINCHES 93.81 MICROMETERS)  
MINIMUM TIN / LEAD (SOLDER) ON COPPER.

2.0 NO JEDEC REGISTRATION AS OF JULY 1996

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FACT™	QST™	
FACT Quiet Series™	Quiet Series™	
FAST®	SuperSOT™-3	
FASTr™	SuperSOT™-6	
GTO™	SuperSOT™-8	
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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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